Product features

●Alcohol free single component room temperature curing silicone adhesive sealant.

●Excellent insulation, moisture resistance, earthquake resistance, corona resistance, electric leakage resistance and chemical medium resistance.

● Good sealing and adhesion to most metal and nonmetal materials.

● Fully meet the requirements of EU directives such as ROHS and REACH.

Typical application

● Thermal conductivity, waterproof, moisture-proof and bonding of sensors, IC integrated modules, radiators, industrial and household electrical equipment, lamps and other products.

●PCB sensitive components, capacitors and triode inductors.
Electronic components such as fixing and bonding. It can also be used for coating protection of pins.

● Metals, plastics, glass and engineering plastics with adhesion requirements.

instructions

1. Clean the surface: clean the surface of the adhered or coated object to remove rust, dust and oil stains.
2. Sizing: cut the front tip, put on a pointed mouth, and use a special glue dispenser or manual glue applicator to size the electronic adhesive on the position of electronic and electrical components to be bonded, generally evenly smeared. According to the product specification, it is allowed to stand and cure to ensure the bonding effect.
3. After the operation is completed, the unused glue should be immediately tightened and sealed.

Version: A0

technical parameter

project	reference standard	KY-HCG 3099W	KY-HCG 3099B	KY-HCG 3099GY	KY-HCG 3099T	KY-HCG 3099ST
colour	estimate range by eye	white	black	grey	transparent	translucence
condition	estimate range by eye	flow			flow	
Relative density (g/cm3)	GB/T533-2008	1.4±0.1			1.0±0.1	
Surface drying time (min)	GB/T13477.5-2002	≤20			≤10	
Hardness (shore A)	GB/T531.1-2008	40±5			30±5	
Elongation at break (%)	GB/T528-2009	≥50			≥50	
Shear strength (MPa)	GB/T7124-2008	≥1.0			≥1.0	
Tensile strength (Mpa)	GB/T528-2009	≥0.6			≥0.6	
Volume resistivity (ω cm)	GB/T1692-2008	≥1.0×1015			≥1.0×1015	
Insulation breakdown strength (Kv/mm)	GB/T1695-2005	≥18			≥18	
Dielectric constant (100MHz)	GB/T1697-2003	4.5			4.5	
Temperature range (°C)	Actual measurement of use environment	-60~200			-60~200	
Viscosity (cps)	GB/T 2794-1995	15,000 to 20,000			1000~2000	

Note: The above performance data are all measured at 25°C and 55% relative humidity after molding for one day. Our company is not responsible for the data difference caused by different test strips or product improvement, and the image may be different from the original product.

matters need attention

1. After the operation is completed, the remaining glue should be sealed and preserved to avoid colloid solidification. When using it again, remove a little crust from the seal before using it.

2. Accidentally contact the skin, wipe it clean, and then rinse it with water; In case of accidental contact with eyes, immediately rinse with clear water and go to the hospital for examination. Please refer to the MSDS of the product for safety data.

Storage requirements

1. This product is non-toxic and non-dangerous, so it can be handled and transported according to general chemicals. Pay attention to seal tightly after use and store in a cool, dry and ventilated place.
2. This product should be stored in RH environment with temperature of 5°C-38°C and humidity of 35%-75% for 6 months.

packing specifications

100ML/ 100 PCs/box;
300ML/ piece, 25 pieces/box; 2.6L/ piece, 4 pieces/box;
Can be customized according to customer requirements.

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